

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Kazunobu MIKI

Serial No.:

Group Art Unit:

Filed: October 10, 2001

Examiner:

For: SEMICONDUCTOR ELEMENT TEST APPARATUS, AND METHOD OF TESTING  
SEMICONDUCTOR ELEMENT USING THE APPARATUS

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, DC 20231

Sir:

Prior to examination of the above-referenced application, please amend the application as follows:

**IN THE DRAWINGS:**

On Page 8 in the "Brief Description of the Drawings", please add the following:

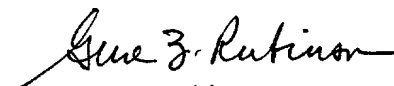
--Fig. 19A and 19B are typical views showing a round-head screw.--

**REMARKS**

The above application is amended to include Figures 19A and 19B in the "Brief Description of the Drawings". Attached hereto is a clean copy of page 8 as amended. Entry of this preliminary amendment is respectfully requested.

Respectfully submitted,

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card according to the first embodiment of the present invention;

Fig. 2A and 2B are typical views showing a round-head screw according to the first embodiment of the present invention;

Fig. 3 is a perspective view showing the probe card at a state to be attached by screws at each mount positions;

Fig. 4 is a perspective view showing the tip end of a reinforcement member according to the second embodiment of the present invention;

Fig. 5 is a side view of a reinforcement member according to the third embodiment of the present invention;

Fig. 6 is a side sectional view of another example of reinforcement members according to the third embodiment of the present invention.

Fig. 7A and 7B are top views showing reinforcement members according to the third embodiment of the present invention;

Fig. 8 is a perspective view showing the constitution of a conventional semiconductor element test apparatus;

Fig. 9 is a perspective view showing a state of contact between a probe needles and a semiconductor element;

Fig. 10 is a perspective view showing a state of contact between the probe needles and an electrode pad;

Fig. 11 is a side view showing a constitution of the prober;

Fig. 12 is a perspective view showing a probe guard having the probe needles mounted thereon;

Fig. 13 is a top view showing the probe guard.

Fig. 14 is a perspective view showing a part of the constitution of the prober;

Fig. 15 is a perspective view showing the constitution of the prober;

Fig. 16 is a perspective view showing a part of the constitution of the prober;

Fig. 17 is a perspective view showing a probe card.

Fig. 18 is a perspective view showing the probe card at the state to be attached by screws.

Fig. 19A and 19B are typical views showing a round-head screw.